Solder wire YS-RMA-NP303

Product description

GENMA solder wire – our YS-RMA-NP303 solder wire convinces with its extremely quick wetting properties in manual soldering. Its quick and excellent wetting properties allow a rapid soldering process, also on difficult surfaces. Cleaning after soldering is not necessary.

Technical properties

	Specific value				Testing method
Diameter (mm)	0,15	0,3	0,5 / 0,6	0,8 / 1,0 / 1,2 / 1,6	
Weight spindle (g)	50	250	500	1000	
Flux type	ROL1, no clean				IPC J-STD-004B
Flux content (wt%)	3,18 ± 0,30 %				IPC-TM-650 2.3.34.1
Halide content (wt%)	0,07 ± 0,03 %				IPC-TM-650 2.3.35
Insulation resistance (Ω)	> 1 x 10^{12} (40°C 90% rel. humidity)				IPC-TM-650 2.6.3.3
Insulation resistance (Ω)	> 1 x 10^{9} (85°C 85% rel. humidity)				IPC-TM-650 2.6.3.3
Migration	non				IPC-TM-650 2.6.14
Recommended solder tip temperature (°C)	330 - 350				
Recommended storage (°C)	0 - 40				

Alloys

Name	Alloy	Melting temperature range	Advantages
NP303	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	217 - 221	Standard alloy, excellent wetting

Compliance

Dated 13.11.2025

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU.

Contains no substances (SVHC-list) more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006.

Contains no substances as defined by the Toxic Substance Control Act (TSCA) of the United States Environmental Protection Agency.

Contains no substances according to POP Regulation EU 2019/1021.

Contains no Per- and PolyFuluoroAlkyl Substances (PFAS).

Contains no phthalates or latex.

Contains no substances according to California Proposition 65.

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